**Amendments to the Claims:**

Please amend the claims to read as follows. This listing of claims replaces all prior versions and listings of claims in the application:

**Listing of Claims:**

1. (Currently amended) A carrier for alignment and attachment of an electronics module to a circuit board, the electronics module having a plurality of leads extending therefrom, the carrier comprising:

a frame having a plurality of sides defining a region to receive the electronics module, the frame having a gap between two of the sides for passage of the leads from the electronics module, at least one of the sides having a first surface configured to maintain contact with a surface of the electronics module when the electronics module is secured to the frame, at least one of the sides having a second surface configured to maintain contact with a ~~first~~ surface of the circuit board when the carrier is secured to the circuit board, the first and second surfaces of the sides being separated by a predetermined distance to position all the leads substantially ~~along a second~~ in contact with the surface of the circuit board; and

a first alignment guide disposed on the frame to align the electronics module to the carrier.

2. (Original) The carrier of claim 1 further comprising a second alignment guide disposed on the frame to align the frame to the circuit board.

3. (Original) The carrier of claim 1 further comprising a capture device disposed on one of the sides of the frame to secure the electronics module to the frame.

4. (Canceled)

5. (Original) The carrier of claim 1 wherein at least one of sides of the frame has an opening to receive a board fastener.

6. (Currently amended) The carrier of claim 3 [[1]] wherein the capture device comprises a resilient stem extending away from the one of the sides of the frame~~, the resilient stem having~~ and a tab at ~~one~~ an end of the resilient stem.

7. (Original) The carrier of claim 1 wherein the electronics module is a laser module.

8. (Original) The carrier of claim 7 further comprising a fiber guide extending from one of the sides opposite the region to receive the laser module.

9. (Original) The carrier of claim 8 further comprising a fiber clip disposed on the fiber guide to secure an optical fiber extending from the laser module to the fiber guide.

10. (Currently amended) The carrier of claim 1 further comprising a wire guide extending from one of the sides ~~the first arm~~ opposite the region to receive the electronics module.

11. (Original) The carrier of claim 10 further comprising a wire clip disposed on the wire guide for attaching at least one wire extending from the electronics module to the wire guide.

12. (Original) The carrier of claim 1 wherein the frame is fabricated from a plastic material.

13. (Original) The carrier of claim 1 wherein the first alignment guide comprises a plurality of alignment posts extending from the first surface of at least one of the sides of the frame to align the electronics module to the frame.

14. (Original) The carrier of claim 2 wherein the second alignment guide comprises a plurality of alignment posts extending from the second surface of at least one of the sides of the frame to align the frame to the circuit board.

15. (Original) A carrier for attachment of a laser module to a circuit board, the laser module having a plurality of leads extending therefrom, the carrier comprising:

a frame having a first side, a second side and a third side in a C-shaped configuration, at least one of the sides having a first surface, at least one of the sides having a second surface, and at least one of the sides having an opening to receive a board fastener, the first and second surfaces being separated by a predetermined distance so that the leads of the laser module are positioned substantially along a surface of the circuit board when the laser module is secured to the carrier and the carrier is secured to the circuit board;

a first plurality of alignment posts disposed on the first surfaces;

a second plurality of alignment posts disposed on the second surfaces;

a capture clip disposed on one of the sides to secure the laser module to the frame; and

a fiber guide extending from one of the sides.

16. (Original) The carrier of claim 15 further comprising a fiber clip disposed on the fiber guide to secure an optical fiber extending from the laser module to the fiber guide.